This listing of claims will replace all prior versions, and the listings of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A wafer area pressure confinement apparatus, comprised of a ring, the ring having a substaintially planar surface, the ring manufactured such that a hanging bore is present within said ring;

~~said~~ the hanging bore further comprising a mating portion to receive and couple said ring to a stepped hanger suspended in a wafer processing chamber;

wherein the hanging bore is attached to an interior of a chamber via chamber plungers capable of vertical adjustment.

Claim 2 (previously amended): The wafer area pressure confinement apparatus of claim 1, further comprising at least one additional hanging bore.

Claim 3 (canceled)

Claim 4 (canceled)

Claim 5 (previously amended): The wafer area pressure confinement apparatus of claim 1, wherein said hanging bore mates and aligns with the hanger.

Claim 6 (original): The wafer area pressure confinement apparatus of claim 1, wherein said ring is manufactured from a dielectric material.

Claim 7 (original): The wafer area pressure confinement apparatus of claim 6, wherein said dielectric material is quartz.

Claim 8 (canceled)

Claim 9 (currently amended) A plasma processing chamber comprising:

means for housing a gaseous medium useful for etching;

a parallel pair of electrodes defining therebetween an interaction space where a plasma capable of etching a workpiece supported on one of the electrodes is generated when radio-frequency energy is provided for establishing a discharge between the electrodes for ionizing the gaseous medium; and

a stack of rings, the rings each having a substaintially planar surface, ~~which~~ are spaced apart from each other by stepped hangars to form slots therebetween and are positioned to surround the interaction space, for controlling the exit of spent gases and for neutralizing charged particles as they exit the interaction space thereby confining the discharge essentially to the interaction space;

the rings capable of being attached to chamber plungers through the use of one of a plurality of hanging bores being suspended on stepped hangers.

Claim 10 (canceled)

Claim 11 (currently amended): The wafer area pressure confinement apparatus of claim 5, wherein the ring is locked to the wafer pressure confinement apparatus by moving the ring vertically relative to the stepped hanger positioned in the hanging bore and then rotating the ring into a locked position.

Claim 12 (currently amended): The wafer area pressure confinement apparatus of claim 1, wherein the stepped hanger comprises at least one step, the step providing a gap between the rings.

Claim 13 (currently amended): The wafer area pressure confinement apparatus of claim 9, wherein the ring is locked to the wafer pressure confinement apparatus by moving the ring vertically relative to the stepped hanger positioned in the hanging bore and then rotating the ring into a locked position.

Claim 14 (currently amended): The wafer area pressure confinement apparatus of claim 9, wherein the stepped hanger comprises at least one step, the step providing a gap between the rings.